

ABSTRACT

SYSTEM FOR REDUCING OXIDATION OF ELECTRONIC DEVICES

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The invention provides a system for reducing oxidation of a semiconductor device when it is heated, for example during wire bonding. A holding device is provided for securing the semiconductor device to a platform. The holding device includes an opening for providing access to an area where the semiconductor device is to be heated and a cavity is coupled to the opening. A gas inlet in fluid communication with the cavity supplies a relatively inert gas to the cavity, whereby to transmit the inert gas to the opening through the cavity and to reduce oxidation of the semiconductor device.

15 (Figure 4)